

#### Is Now Part of



# ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at <a href="https://www.onsemi.com">www.onsemi.com</a>

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



October 2013

## FCH47N60F

# N-Channel SuperFET® FRFET® MOSFET

**600 V, 47 A, 73 m** $\Omega$ 

#### **Features**

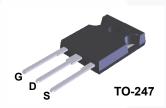
- 650 V @ T<sub>.I</sub> = 150 °C
- Typ. R<sub>DS(on)</sub> = 58 mΩ
- Ultra Low Gate Charge (Typ.  $Q_g$  = 210 nC)
- Low Effective Output Capacitance (Typ. Cosseff. = 420 pF)
- · 100% Avalanche Tested
- RoHS Compliant

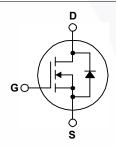
#### **Applications**

- Solar Inverter
- AC-DC Power Supply

## **Description**

SuperFET® MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server / telecom power, FPD TV power, ATX power and industrial power applications. SuperFET FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





## Absolute Maximum Ratings $T_C = 25$ °C unless otherwise noted

Symbol	Parameter		FCH47N60F_F133	Unit	
V <sub>DSS</sub>	Drain-Source Voltage		600	V	
I <sub>D</sub>	Drain Current - Continuous ( $T_C = 25^{\circ}C$ ) - Continuous ( $T_C = 100^{\circ}C$ )		47 29.7	A A	
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	141	Α	
V <sub>GSS</sub>	Gate-Source voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	1800	mJ	
I <sub>AR</sub>	Avalanche Current	(Note 1)	47	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	41.7	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	50	V/ns	
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C				
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	FCH47N60F_F133	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.3	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	41.7	°C/W	

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH47N60F	FCH47N60F_F133	TO-247	-	-	30

## **Electrical Characteristics** $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 25°C	600			V
	$V_{GS} = 0V$ , $I_D = 250\mu A$ , $T_J = 150^{\circ} C$		650		V	
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C		0.6		V/°C
BV <sub>DS</sub>	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0V$ , $I_D = 47A$		700		V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 480V, T <sub>C</sub> = 125°C			10 100	μ <b>Α</b> μ <b>Α</b>
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V			-100	nA
On Charac	cteristics			•		
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 23.5A	-	0.062	0.073	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 23.5A	\	40		S
Dynamic C	Characteristics			•	•	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz		5900	8000	pF
C <sub>oss</sub>	Output Capacitance			3200	4200	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			250		pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 480V, V <sub>GS</sub> = 0V, f = 1.0MHz		160		pF
C <sub>oss</sub> eff.	Effective Output Capacitance	V <sub>DS</sub> = 0V to 400V, V <sub>GS</sub> = 0V		420		pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 300V, I_{D} = 47A$ $R_{G} = 25\Omega$	/	185	430	ns
t <sub>r</sub>	Turn-On Rise Time			210	450	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		/	520	1100	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		75	160	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 480V, I <sub>D</sub> = 47A V <sub>GS</sub> = 10V		210	270	nC
Q <sub>gs</sub>	Gate-Source Charge			38	//	nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)		110		nC
Drain-Sou	rce Diode Characteristics and Maximur	n Ratings			•	
I <sub>S</sub>	Maximum Continuous Drain-Source Dio	de Forward Current			47	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	orward Current			141	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 47A			1.4	٧
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>S</sub> = 47A		240		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt =100A/μs		2.04		μС

#### NOTES

<sup>1.</sup> Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup>  $I_{AS}$  = 18A,  $V_{DD}$  = 50V,  $R_G$  = 25 $\Omega$ , Starting  $T_J$  = 25 $^{\circ}C$ 

<sup>3.</sup>  $I_{SD} \le 47 \text{A}$ , di/dt  $\le 1200 \text{A}/\mu \text{s}$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J$  = 25°C

<sup>4.</sup> Essentially Independent of Operating Temperature Typical Characteristics

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

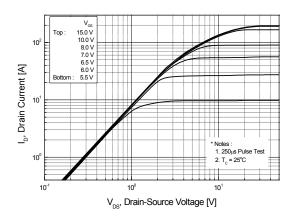


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

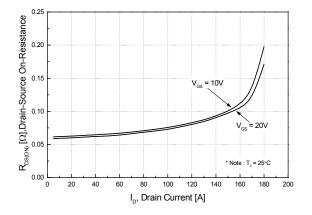


Figure 2. Transfer Characteristics

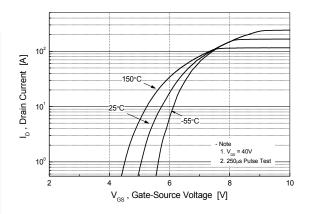
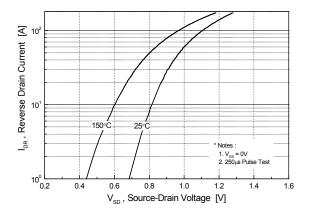


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue



**Figure 5. Capacitance Characteristics** 

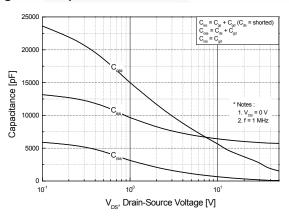
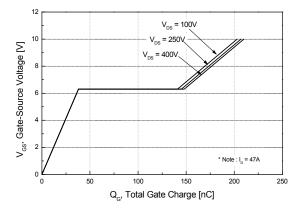


Figure 6. Gate Charge Characteristics



### **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

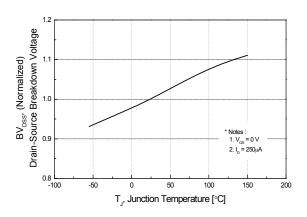


Figure 8. On-Resistance Variation vs. Temperature

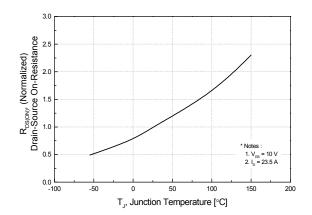


Figure 9. Safe Operating Area

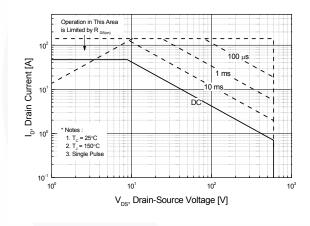


Figure 10. Maximum Drain Current vs. Case Temperature

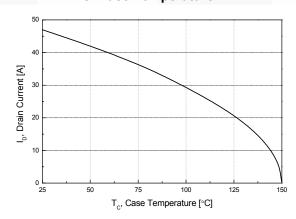


Figure 11. Transient Thermal Response Curve

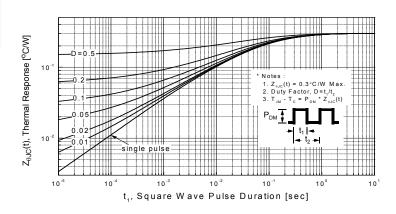


Figure 12. Gate Charge Test Circuit & Waveform

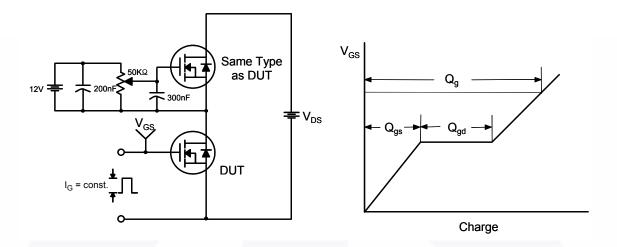


Figure 13. Resistive Switching Test Circuit & Waveforms

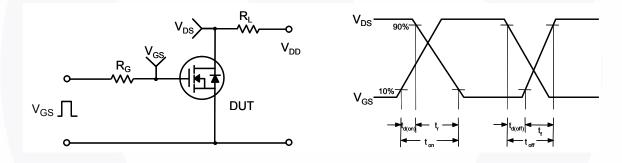
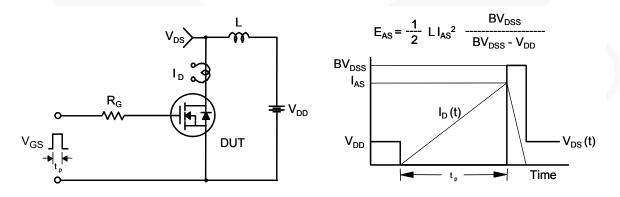


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



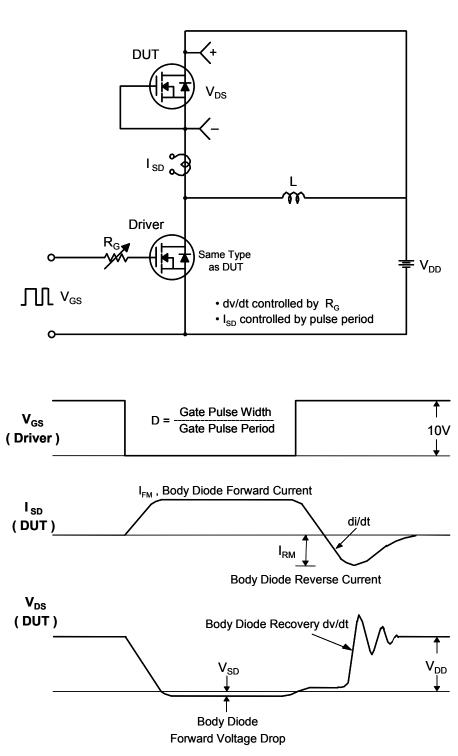
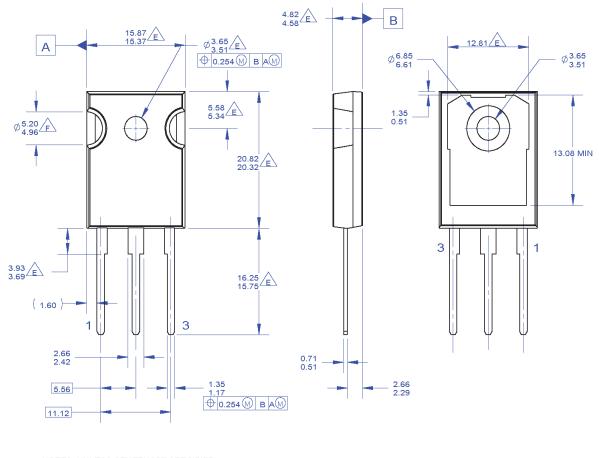


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### **Mechanical Dimensions**

## TO-247 3L



NOTES: UNLESS OTHERWISE SPECIFIED

- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5 1994

DOES NOT COMPLY JEDEC STANDARD VALUE

NOTCH MAY BE SQUARE

G. DRAWING FILENAME: MKT-TO247A03\_REV03

#### Figure 16. TO-247, Molded, 3 Lead, Jedec Variation AB

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

http://www.fairchildsemi.com/package/packageDetails.html?id=PN\_TO247-003

Dimension in Millimeters





#### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ AX-CAP® BitSiC™ Build it Now™ CorePLUS™ CorePOWER™  $CROSSVOLT^{\text{TM}}$ 

CTI ™ Current Transfer Logic™ DEUXPEED® Dual Cool™ EcoSPARK®

EfficentMax™ ESBC™

FACT Quiet Series™ FACT® FAST® FastvCore™

Fairchild<sup>®</sup> Fairchild Semiconductor® FETBench™ FPS™

FRFET® Global Power Resource<sup>SM</sup> GreenBridge™ Green FPS™

Green FPS™ e-Series™

G*max*™ GTO™ IntelliMAX™ ISOPLANAR™

F-PFS™

Marking Small Speakers Sound Louder

and Better™ MegaBuck™ MICROCOUPLER™ MicroFET™ MicroPak™ MicroPak2™

MillerDrive™ MotionMax™ mWSaver® OptoHiT™ OPTOLOGIC® OPTOPLANAR® PowerTrench® PowerXS™

Programmable Active Droop™

**QFET** QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax™ SMART START™

Solutions for Your Success™

STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6

SuperSOT™-8 SupreMOS® SvncFET™

Sync-Lock™ SYSTEM ®\* TinyBoost<sup>®</sup> TinyBuck<sup>®</sup> TinyCalc™ TinyLogic<sup>®</sup> TINYOPTO™ TinvPower™ TinyPWM™ TinyWire™ TranSiC™ TriFault Detect™ TRUECURRENT®\* μSerDes™

UHC<sup>®</sup> Ultra FRFET™ UniFFT™ VCX™ VisualMax™ VoltagePlus™ XS™

\*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY
FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE
EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS Definition of Terms

Datasheet Identification Product Status		Definition		
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specification may change in any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
No Identification Needed Full Production		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete Not In Production		Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev 166

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative